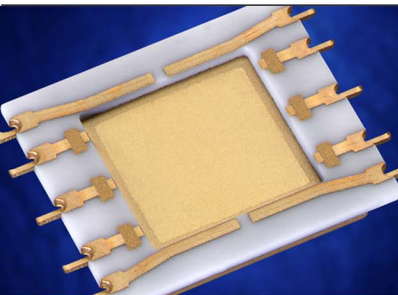
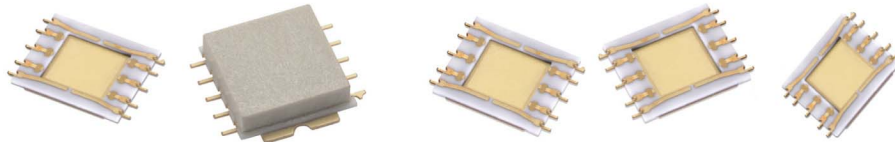


SURFACE MOUNT PACKAGES

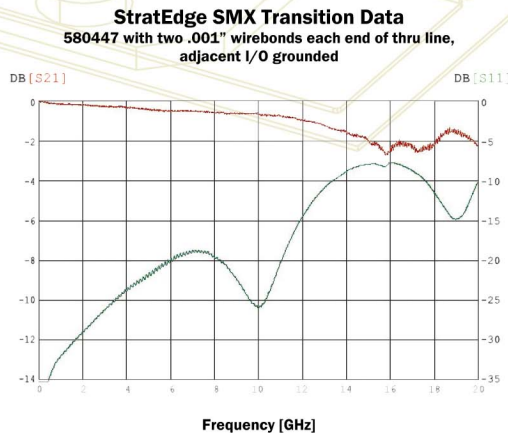
HIGH FREQUENCY
AND
HIGH SPEED
PACKAGING



StratEdge SMX packages are DC to 18 GHz surface mount designs. Their leads are co-planar with their base. Unlike packages that are mounted in a hole in the circuit board, SMX packages mount directly on the board, reducing circuit board assembly costs. Surface mount packages also simplify the board layout and significantly reduce board design costs.

The SMX Series incorporates a conductive metal base attached to an alumina ceramic ring frame. The base and the leads are attached using high temperature copper silver braze. These packages are sealed using a cup-shaped lid with a b-stage epoxy preform. The copper composite base is smaller and thinner than the bases in most ceramic package designs so they are less expensive than other flanged packages with large metal bases.

SMX packages are very low loss from DC to 18 GHz. This performance range makes them ideal for next generation test and measurement equipment, WiMax and VSAT amplifiers, point-to-point and point-to-multipoint radios, and any high power application where surface mount packages are desired.



- **Low cost surface mount microwave packages**
- **High thermal conductivity base**
- **Excellent electrical properties through Ku band**
- **Supplied with cup-shaped lid with attached epoxy seal**
- **Perfect for C, X, and Ku band amplifiers**

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PN	Outside Overall Dimensions	Outside Ceramic	Cavity Dimensions	Lid PN	I/O's	Bolt Hole
580447	.335" x .310"	.270" x .270"	.155" x .125"	200045	6RF, 4DC	Yes
580448	.438" x .315"	.373" x .315"	.250" x .220"	200102	6RF, 4DC	No
580472	.335" x .310"	.270" x .270"	.053" x .043"	200076	4RF	Yes

Other custom configurations available upon request. Please consult factory.

U.S. Patent#s: 6,639,305; 6,271,579; 6,172,412; 5,448,826; 5,465,008, 5,692,298, 5,753,972, 5,736,783; 6,261,867; 09/054,049 & other patents pending
Foreign Patent#s: NI 091074; NI 118360; NI 186089; EP 0902976; AT 220245; AU 199724473; AU 199726655; AU 199918149; DE 69713771; EP 0902975; JP 2000510286; JP 2000510287; TW 322612; TW 4000590; TW 554451; WO 199743786; WO 199743787; WO 199934443; WO 2002063684 & other patents pending

